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**Electronic Patent Application Submission**  
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Application ID: 10665651 \*10665651\*

Title of Invention: THIN AND HEAT RADIANT  
SEMICONDUCTOR PACKAGE AND  
METHOD FOR MANUFACTURING

First Named Inventor: Jae Ku

Domestic/Foreign Application: Domestic Application

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## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING</b>	
Application Number: 10/665651 *10/665651*		
Date: 2003-09-19		
First Named Applicant: Jae Hun Ku		
Confirmation Number: 6079		
Attorney Docket Number: AMKOR041G		
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<b>Submitted by:</b>	<b>Elec. Sign.</b>	<b>Sign. Capacity</b>
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

<b>Documents being submitted</b> us-ids	<b>Files</b> ids4-usidst.xml us-ids.dtd us-ids.xsl
<b>Comments</b>	

**ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	<b>THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING</b>						
 Application Number: 10/665651 <span style="float: right;">*10/665651*</span> Confirmation Number: 6079 First Named Applicant: Jae Ku Attorney Docket Number: AMKOR041G Art Unit: 2811 Search string: ( 5909053 or 5915998 or 5917242 or 5939779 or 5942794 or 5951305 or 5959356 or 5969426 or 5973388 or 5976912 or 5977613 or 5977615 or 5977630 or 5981314 or 5986333 or 5986885 or 6001671 or 6013947 or 6018189 or 6020625 or 6025640 or 6031279 or RE36613 or 6034423 or 6040626 or 6043430 or 6060768 or 6060769 or 6072228 or 6075284 or 6081029 or 6084310 or 6087715 or 6087722 or 6100594 or 6113474 or 6118174 or 6118184 or 6130115 or 6130473 or RE36907 or 6133623 or 6140154 or 6143981 or 6169329 or 6177718 or 6181002 or 6184465 or 6184573 or 6194777 ).pn.  <b>US Patent Documents</b>  Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5909053	1999-06-01	FUKASE ET AL.			
	2	5915998	1999-06-29	STIDHAM ET AL.			
	3	5917242	1999-06-29	BALL			
	4	5939779	1999-08-17	KIM			
	5	5942794	1999-08-24	OKUMURA ET AL.			
	6	5951305	1999-09-14	HABA			
	7	5959356	1999-09-28	OH			
	8	5969426	1999-10-19	BABA ET AL.			
	9	5973388	1999-10-26	CHEW ET AL.			
	10	5976912	1999-11-02	FUKUTOMI ET AL.			
	11	5977613	1999-11-02	TAKATA ET AL			

	12	5977615	1999-11-02	YAMAGUCHI ET AL.
	13	5977630	1999-11-02	WOODWORTH ET AL.
	14	5981314	1999-11-09	GLENN ET AL.
	15	5986333	1999-11-16	NAKAMURA
	16	5986885	1999-11-16	WYLAND
	17	6001671	1999-12-14	FJELSTAD
	18	6013947	2000-01-11	LIM
	19	6018189	2000-01-25	MIZUNO
	20	6020625	2000-02-01	QIN ET AL.
	21	6025640	2000-02-15	YAGI ET AL.
	22	6031279	2000-02-29	LENZ
	23	RE36613	2000-03-14	BALL
	24	6034423	2000-03-07	MOSTAFAZADEH
	25	6040626	2000-03-21	CHEAH ET AL.
	26	6043430	2000-03-28	CHUN
	27	6060768	2000-05-09	HAYASHIDA ET AL.
	28	6060769	2000-05-09	WARK
	29	6072228	2000-06-06	HINKLE ET AL.
	30	6075284	2000-06-13	CHOI ET AL.
	31	6081029	2000-06-27	YAMAGUCHI
	32	6084310	2000-07-04	MIZUNO ET AL.
	33	6087715	2000-07-11	SAWADA ET AL.
	34	6087722	2000-07-11	LEE ET AL.
	35	6100594	2000-08-08	FUKUI ET AL.
	36	6113474	2000-09-05	COSTANTINI ET AL.
	37	6118174	2000-09-12	KIM
	38	6118184	2000-09-12	ISHIO ET AL.
	39	6130115	2000-10-10	OKUMURA ET AL.
	40	6130473	2000-10-10	MOSTAFAZADEH ET AL.
	41	RE36907	2000-10-10	TEMPLETON, JR ET AL
	42	6133623	2000-10-17	OTSUKI ET AL.
	43	6140154	2000-10-31	HINKLE ET AL
	44	6143981	2000-11-07	GLENN
	45	6169329	2001-01-02	FARNWORTH ET AL
	46	6177718	2001-01-23	KOZONO
	47	6181002	2001-01-30	JUSO ET AL

	48	6184465	2001-02-06	CORISIS
	49	6184573	2001-02-06	PU
	50	6194777	2001-02-27	ABBOTT ET AL

Signature

Examiner Name	Date